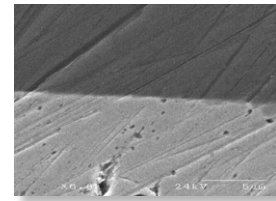
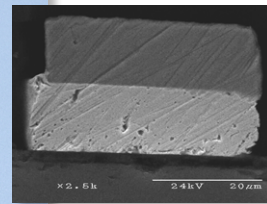
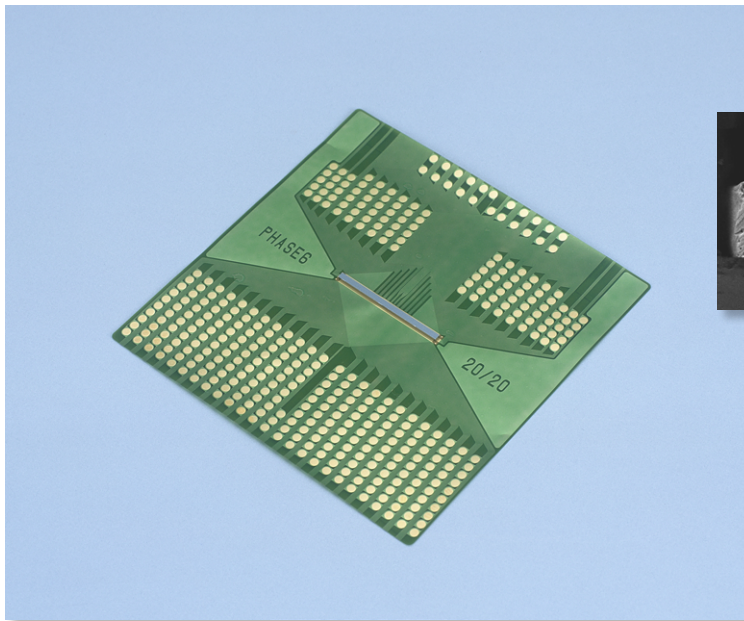


Ultrasound Flip-Chip Bonding Application

Chip On Film substrate



(Magnified bonded cross section)

Chip size ; 20.05 x 1.06 x 0.42 mm

Chip bump ; Au plated 770 pins

Bump pitch ; 40 (30) μm

Substrate ; Au plated pads on 2 layers of film



model FCB-SH50MP
Semi-automatic
Flip-Chip Bonder

ULTEX
SoundPower Laboratory